



Spec No.:

Created Date: 2016/4/21 Revision: (PRELIMINARY) - 1.0



SMD LED

LTSA-2835ZAET

Rev	<u>Description</u>	<u>By</u>	<u>Date</u>
1.0	New data sheet	Andy Chia	4/21/2016
	Above data for PD and Customer track	ing only	

Customer Name:						
Customer Signature:	Print Name:					
LiteON Sales Signature:	Print Name:					



1. Description

SMD LEDs from Lite-On are available in miniature sizes and special configurations for automated PC board assembly and space-sensitive applications. These SMD LEDs are suitable for use in a wide variety of electronic equipment, including cordless and cellular phones, notebook computers, network systems etc.

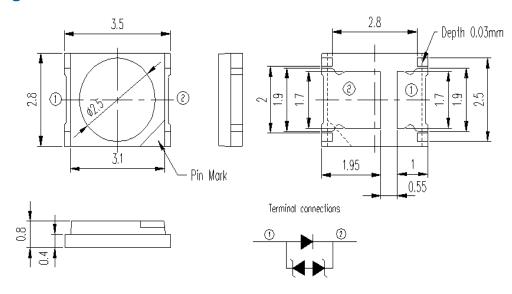
1.1 Features

- Package in 8mm tape on 7" diameter reels
- EIA STD package
- I.C. compatible
- Compatible with automatic placement equipment
- Compatible with infrared reflow solder process
- Preconditioning: accelerate to JEDEC level 3

1.2 Applications

Aftermarket: accessory application,

2. Package Dimensions



Part No.	Lens Color	Source Color
LTSA-2835ZAET	Orange	InGaN Yellow

Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ±0.2 mm (.008") unless otherwise noted.



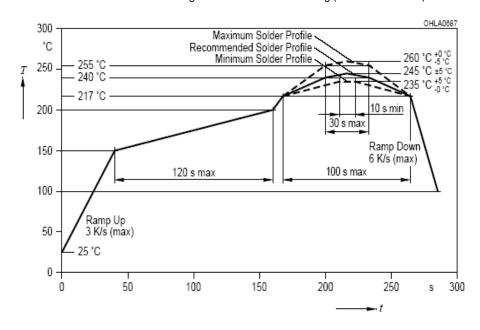
3. Rating and Characteristics

3.1 Absolute Maximum Ratings at Ta=25°C

Parameter	LTSA-2835ZAET	Unit
Power Dissipation	510	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	300	mA
DC Forward Current	150	mA
Operating Temperature Range	-40°C to + 100°C	
Storage Temperature Range	-40°C to + 100°C	

3.2 Suggest IR Reflow Condition for Pb Free Process:

IR-Reflow Soldering Profile for lead free soldering (Acc. to J-STD-020)





3.3 Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Part No. LTSA-	Min.	Тур.	Max.	Unit.	Test Condition
Luminous Flux	ФV	2835ZAET	35.0	-	55.0	Lm	IF = 150mA Note 1
Viewing Angle	2 θ _{1/2}	2835ZAET		120		deg	Note 2 (Fig.2)
Characticity Coordinates	х	2835ZAET		0.5775			IF = 150mA
Chromaticity Coordinates	у	2835ZAET		0.4132		-	Note 3
Forward Voltage	VF	2835ZAET	2.8	-	3.6	V	IF = 150mA
Reverse Current	IR	2835ZAET	-	-	10	μΑ	VR = 5V Note 4

Notes:

- Luminous intensity is measured with a light sensor and filter combination that approximates the CIE
 eye-response curve
- 2. θ 1/2 is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The chromaticity coordinates (x , y) is derived from the 1931 CIE chromaticity diagram
- 4. Reverse voltage (VR) condition is applied to IR test only. The device is not designed for reverse operation.



4. Bin Rank

4.1 VF Rank

Forward ^v	Voltage Unit : Vf @	150mA
Bin Code	Min.	Max.
D7	2.8	3.0
D8	3.0	3.2
D9	3.2	3.4
D10	3.4	3.6

Tolerance for each forward voltage bin is +/- 0.1 volt

4.2 IV Rank

Luminou	s Flux Unit : Im @1	50mA
Bin Code	Min.	Max.
A7	35	40
A8	40	45
А9	45	50
A10	50	55

Tolerance on each Intensity bin is +/-15%

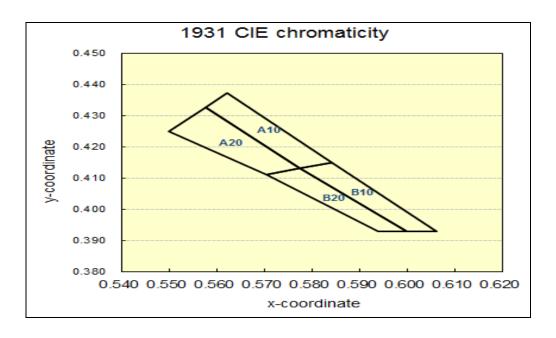


4.3 Color Rank

Color Bin Table					Tes	t @	150mA				
Bin Code	Color Bin Limits				Bin		Color Bin Limits				
	CIE-	Point1	Point2	Point3	Point4	Code	CIE-	Point1	Point2	Point3	Point4
A40	х	0.5775	0.5843	0.5622	0.5576	420	х	0.5705	0.5775	0.5576	0.5499
A10	у	0.4132	0.4151	0.4372	0.4326	A20	у	0.4111	0.4132	0.4326	0.4249
B10	х	0.5775	0.5843	0.6062	0.5982	Dan	х	0.5705	0.5775	0.6000	0.5940
	у	0.4132	0.4151	0.3930	0.3930	B20	у	0.4111	0.4132	0.3930	0.3930

Tolerance on each Hue bin (x, y) bin is \pm -0.01.

4.4 Chromaticity Coordinate





5. Typical Electrical / Optical Characteristics Curves.

(25°C Ambient Temperature Unless Otherwise Noted)

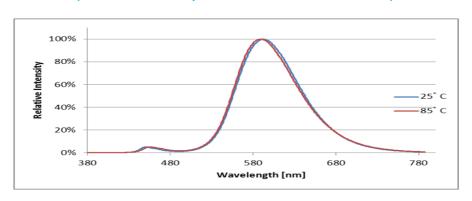


Fig. 1 RELATIVE INTENSITY VS. WAVELENGTH

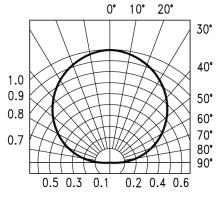


Fig. 2 SPATIAL DISTRIBUTION

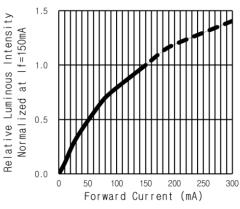


Fig. 4 RELATIVE LUMINOUS INTENSITY
V.S. FORWARD CURRENT

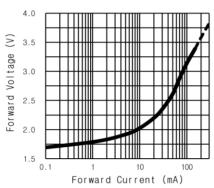


Fig. 3 FORWARD VOLTAGE V.S. FORWARD CURRENT

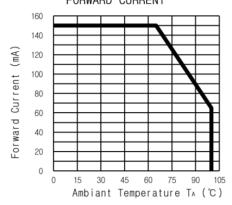


Fig.5 FORWARD CURRENT DERATING CURVE



6. User Guide

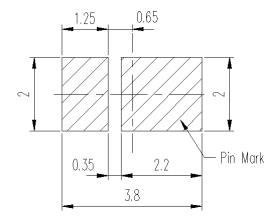


6.1 Cleaning

Do not use unspecified chemical liquid to clean LED they could harm the package.

If clean is necessary, immerse the LED in ethyl alcohol or in isopropyl alcohol at normal temperature for less one minute.

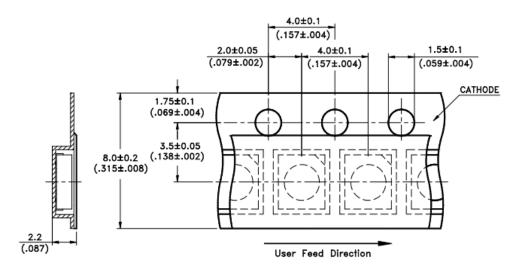
6.2 Recommend Printed Circuit Board Attachment Pad



Note:

1. Suggest stencil thickness is maximum 0.10mm.

6.3 Package Dimensions Of Tape And Reel

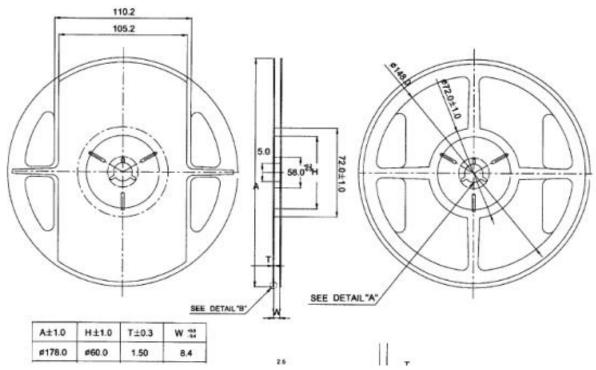


Note:

1. All dimensions are in millimeters (inches).



6.4 Package Dimensions of Reel



Notes:

- 1. Empty component pockets sealed with top cover tape.
- 2. 7 inch reel-2000 pieces per reel.
- 3. Minimum packing quantity is 500 pieces for remainders.
- 4. The maximum number of consecutive missing lamps is two.
- 5. In accordance with EIA-481 specifications.

7. Cautions



7.1 Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

7.2 Storage

The package is sealed:

The LEDs should be stored at 30°C or less and 70%RH or less. And the LEDs are limited to use within one year, while the LEDs is packed in moisture-proof package with the desiccants inside.

The package is opened:

The storage ambient for the LEDs should not exceed 30°C temperature and 60% relative humidity.

It is recommended that LEDs out of their original packaging are IR-reflowed within 168hrs.

For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant, or in a desiccators with nitrogen ambient.

LEDs stored out of their original packaging for more than 168hrs should be baked at about 60 °C for at least 48 hours before solder assembly.

7.3 Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED if necessary.

7.4 Soldering

Recommended soldering conditions:

Reflo	w soldering	Soldering iron		
Pre-heat	150~200°C	Temperature	300°C Max.	
Pre-heat time	120 sec. Max.	Soldering time	3 sec. Max.	
Peak temperature	260°C Max.		(one time only)	
Soldering time	10 sec. Max.(Max. two times)			

Notes:

Because different board designs use different number and types of devices, solder pastes, reflow ovens, and circuit boards, no single temperature profile works for all possible combinations.

However, you can successfully mount your packages to the PCB by following the proper guidelines and PCB-specific characterization.

LITE-ON Runs both component-level verification using in-house **KYRAMX98** reflow chambers and board-level assembly. The results of this testing are verified through post-reflow reliability testing .Profiles used at LITE-ON are based on JEDEC standards to ensure that all packages can be successfully and reliably surface mounted.

Figure on page3 shows a sample temperature profile compliant to JEDEC standards. You can use this example as a generic target to set up your reflow process. You should adhere to the JEDEC profile limits as well as specifications and recommendations from the solder paste manufacturer to avoid damaging the device and create a reliable solder joint.

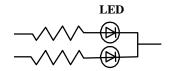
7.5 Drive Method

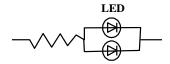
A LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.



Circuit model A

Circuit model B





- (A) Recommended circuit.
- (B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

7.6 ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

Suggestions to prevent ESD damage:

- Use of a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- All devices, equipment, and machinery must be properly grounded.
- Work tables, storage racks, etc. should be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LED's plastic lens as a result of friction between LEDs during storage and handling.

ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no lightup" at low currents.

To verify for ESD damage, check for " lightup " and Vf of the suspect LEDs at low currents.

The Vf of "good" LEDs should be >2.0V@0.1mA for InGaN product and >1.4V@0.1mA for AllnGaP product.

8. Reliability Test

condition Sa	Test item		No.	N
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1	Pre-conditioning	MSL 3 125°C, 24 hrs baking Moisture Soak 60°C/60% 52 hrs Interval: 15mins ~ 4 hours to do IR-Reflow	240	JESD22 A-113
2	High Temperature Operating Life I	IF=150mA, Ta=65°C., 1000 hrs	30	EIAJ ED-4701/100 (101)
3	High Temperature Operating Life II	Ta=100°C., IF=65mA 1000 hr	30	EIAJ ED-4701/100 (101)
4	Low Temperature Operating Life	Ta=-40°C., IF=150mA, 1000 hrs	30	EIAJ ED-4701/100 (101)
5	High Temperature Storage	Ta=100°C., 1000 hrs	30	EIAJ ED-4701/200 (201)
6	Low Temperature Storage	Ta= -40°C., 1000 hrs	30	EIAJ ED-4701/200 (202
7	High Temperature High Humidity Bias (HTHHB)	Ta=60°C, Rh=90%, IF=150mA, 1000 hrs	30	EIAJ ED-4701/100 (102)
8	Thermal Shock (air to air)	-40°C ± 5°C ~ 100 ± 5°C 30min 30min 300cycles	30	EIAJ ED-4701/300 (307)
9	Temperature Cycle	-40°C ~ 25°C ~ 100°C ~ 25°C 30min 5min 30min 5min 300cycles	30	EIAJ ED-4701/100 (105)
10	Resistance to Soldering Heat	Level 3 (1) Bake 125°C / 24 hours (2) Acceleration moisture soak condition (if urgent): 60°C / 60% / 52 hours (Interval: 15mins ~ 4 hours to do IR-Reflow) (3) IR Reflow 3 times (260°C: 10 secs, Interval: 5 mins ~ 60 mins for each reflow)	30	EIAJ ED- 4701/300 (301 & 302)

9. Others

The appearance and specifications of the product may be modified for improvement without prior notice.

10. Suggested Checking List

Training and Certification



- 1. Everyone working in a static-safe area is ESD-certified?
- 2. Training records kept and re-certification dates monitored?

Static-Safe Workstation & Work Areas

- 1. Static-safe workstation or work-areas have ESD signs?
- 2. All surfaces and objects at all static-safe workstation and within 1 ft measure less than 100V?
- 3. All ionizer activated, positioned towards the units?
- 4. Each work surface mats grounding is good?

Personnel Grounding

- 1. Every person (including visitors) handling ESD sensitive (ESDS) items wears wrist strap, heel strap or conductive shoes with conductive flooring?
- 2. If conductive footwear used, conductive flooring also present where operator stand or walk?
- 3. Garments, hairs or anything closer than 1 ft to ESD items measure less than 100V*?
- 4. Every wrist strap or heel strap/conductive shoes checked daily and result recorded for all DLs?
- 5. All wrist strap or heel strap checkers calibration up to date?

Note: *50V for InGaN LED.

Device Handling

- 1. Every ESDS items identified by EIA-471 labels on item or packaging?
- 2. All ESDS items completely inside properly closed static-shielding containers when not at static-safe workstation?
- 3. No static charge generators (e.g. plastics) inside shielding containers with ESDS items?
- 4. All flexible conductive and dissipative package materials inspected before reuse or recycles?

Others

- 1. Audit result reported to entity ESD control coordinator?
- 2. Corrective action from previous audits completed?
- 3. Are audit records complete and on file?

Part No. : LTSA-2835ZAE BNS-OD-FC002/A4